

## C1206F105K3RACTU

**Specifications** 

Insulation Resistance

Aliases (C1206F105K3RAC7800) SMD Comm X7R FO, Ceramic, 1 uF, 10%, 25 VDC, X7R, SMD, MLCC, Open Mode, Temperature Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X7R FO
Style	SMD Chip
Description	SMD, MLCC, Open Mode, Temperature Stable
Features	Open Mode, Temperature Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	25 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
Т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

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W	1.6mm +/-0.2mm
Т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.5mm +/-0.25mm
Packaging Specifications	

	Capacitance	1uF
	Measurement Condition	1 kHz 1.0Vrms
	Tolerance	10%
	Voltage DC	25 VDC
	Dielectric Withstanding Voltage	62.5 VDC
	Temperature Range	-55/+125°C
	Temp. Coefficient	X7R
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
	Dissipation Factor	3.5% 1 kHz 1.0Vrms
	Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours

500 MOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

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